

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	17	(high and low)adj resistive adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2006/03/07 13:52
L2	48	(high and low)adj resistive near2 layer	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2006/03/07 14:19
L3	9	("20030073301"   "5693363"   "5744394"   "5904565"   "5909563"   "5913144"   "5953634"   "6403465"   "6436825").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/07 13:55
L5	257	(cu copper) adj oxide with barrier adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/03/07 15:40
L6	0	438/654.clss.	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/03/07 15:41
L7	373	(438/654).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2006/03/07 15:41
L8	2267160	resistive resistance resistivity conductivity conductive&3 and 7	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2006/03/07 15:42
L9	273	(resistive resistance resistivity conductivity conductive&3) and 7	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2006/03/07 15:42
L10	179	(resistive resistance resistivity conductivity conductive&3) and 7 and (cu copper)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2006/03/07 15:43
L11	99	(lower reduce) same (resistive resistance resistivity conductivity conductive&3) and 7 and (cu copper)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2006/03/07 15:48
L12	51	(lower reduce) same (resistive resistance resistivity conductivity conductive&3) and 7 and (cu copper)same oxide	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2006/03/07 15:49

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L13	36	(lower reduce) same (resistive resistance resistivity conductivity conductive&3) and 7 and (cu copper)with oxide	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2006/03/07 15:53
L14	529	(diffusion near1 barrier) adj layer treat\$3 (copper or metal) adhesion	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	OFF	2006/03/07 15:59
L15	62364	barrier.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	OFF	2006/03/07 15:58
L16	319	15 and 14	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	OFF	2006/03/07 15:58
L17	123	(diffusion near1 barrier) adj layer (treat or treating or treatment) (copper or metal) adhesion.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	OFF	2006/03/07 16:00
L18	23	((diffusion near1 barrier) adj layer (treat or treating or treatment) (copper or metal) adhesion).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	OFF	2006/03/07 16:03